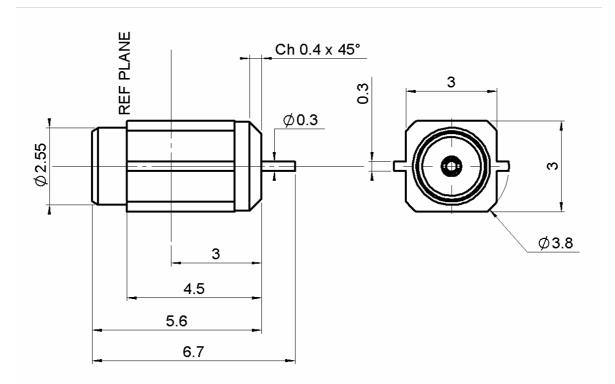
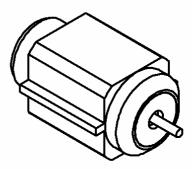
### **REEL OF 400**

# R199.005.800

Series: MC-CARD







All dimensions are in mm.

COMPONENTS	MATERIALS	PLATINGS (μm)	
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER - PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 0.8 OVER NICKEL 2	

**Issue:** 1101 F



**REEL OF 400** 

## R199.005.800

Series: MC-CARD

### **PACKAGING**

Standard	Unit	Other
400	'W' option	Contact us

### **SPECIFICATION**

### **ELECTRICAL CHARACTERISTICS**

Impedance  $50 \Omega$ 

Frequency **0-8** GHz

VSWR 1.15 + 0,0150 x F(GHz) Maxi

Insertion loss .07  $\sqrt{F(GHz)}$  dB Maxi

RF leakage - ( - F(GHz)) dB Maxi Voltage rating 170 Veff Maxi

Voltage rating
Dielectric withstanding voltage
Insulation resistance 500 Veff mini 5000 MΩ mini

#### **ENVIRONMENTAL**

Operating temperature -65/+165 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

### **OTHERS CHARACTERISTICS**

Assembly instruction

Others:

#### MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 5000 Cycles mini

Weight **0,2470** g

**Issue:** 1101 F

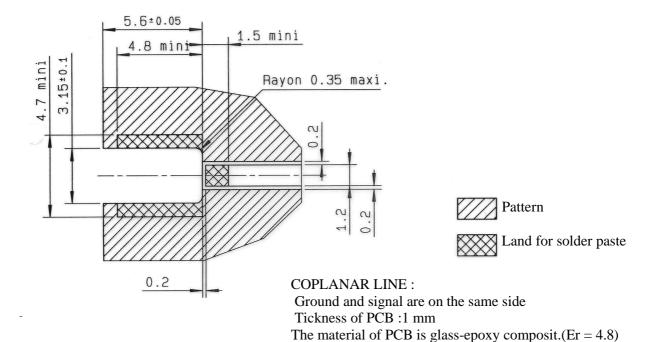


### **REEL OF 400**

# R199.005.800

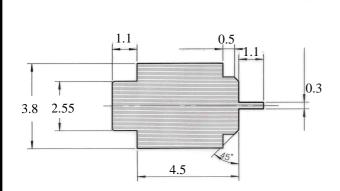
Series: MC-CARD

### **INFORMATIONS**



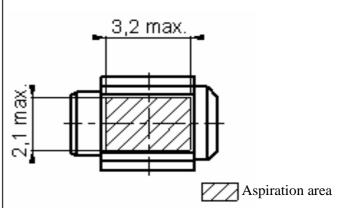
pattern on the PCB.

### SHADOW OF RECEPTACLE FOR VIDEO CAMERA



#### ASPIRATION AREA

The solder resist should be printed except for the land



**Issue:** 1101 F

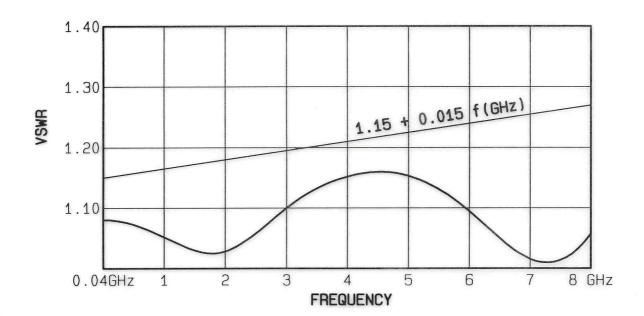


**REEL OF 400** 

R199.005.800

Series: MC-CARD

R199 005 504 CONNECTED WITH R199 005 200



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In the effort to improve our products, we reserve the right to make changes judged to be necessary.



### **REEL OF 400**

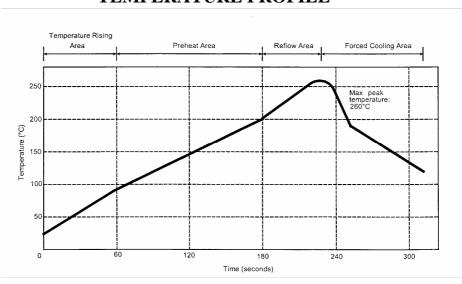
R199.005.800

Series: MC-CARD

### **SOLDER PROCEDURE**

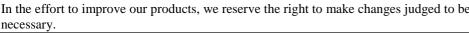
- 1. Deposition of solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
  - We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- Cleaning of printed circuit boards.
- Checking of solder joints and position of the component by visual inspection.

### TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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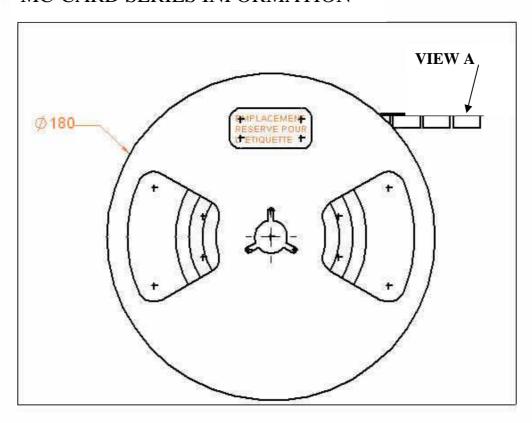


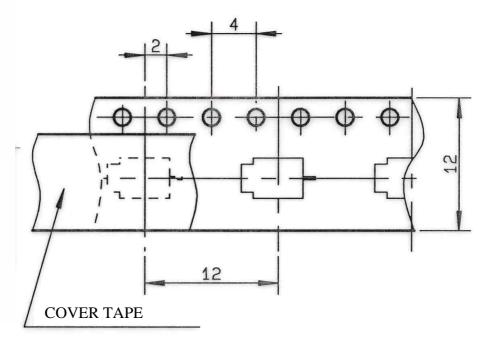
**REEL OF 400** 

# R199.005.800

Series: MC-CARD

## MC-CARD SERIES INFORMATION





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